

Title (en)

Method for the production of wafers with defective-poor surfaces, the use such wafers and therewith obtained electronic units

Title (de)

Verfahren zur Herstellung von Wafern mit defektarmen Oberflächen, die Verwendung solcher Wafer and damit erhaltene elektronische Bauteile

Title (fr)

Procédé de production de plaquettes semiconductrices comprenant des surfaces pauvres en défauts, l'utilisation de telles plaquettes et les ensembles électroniques ainsi obtenus

Publication

EP 1570951 A3 20060405 (DE)

Application

EP 05004484 A 20050301

Priority

DE 102004010379 A 20040303

Abstract (en)

[origin: EP1570951A2] The method involves polishing the surface with a polishing tool (40,60)) in constantly changing different polishing directions so that each place of the surface is covered statistically uniformly in each direction of a 360 degree complete angle. Independent claim describes substrate wafer for defect-free semi conductor component polished as above. Independent claim describes use of wafer (10) for manufacturing electronic components using high energy and high temperature technology. Independent claim describes electronic semiconductor component comprising substrate and one or more defect-free layers of semi conductor materials arranged thereon.

IPC 8 full level

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CPC (source: EP US)

B24B 37/042 (2013.01 - EP US); **B24B 37/30** (2013.01 - EP US)

Citation (search report)

- [A] EP 0008360 A1 19800305 - IBM [US]
- [X] ANONYMOUS: "Method Of Polishing Semiconductor Wafers. September 1979.", IBM TECHNICAL DISCLOSURE BULLETIN, vol. 22, no. 4, 1 September 1979 (1979-09-01), New York, US, pages 1453, XP002366198

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DOCDB simple family (publication)

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DOCDB simple family (application)

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